

ABSTRACT

In a manufacturing method of a printed circuit board comprising a process of forming a circuit pattern on the surface of the base substrate (13) of which surface is at least composed of an insulative material, a process of forming the insulative layer (15) composed of mixed composites of more than two kinds of organic resins having a different etching rate by a dry etching process on the surface of the base substrate (13) including the circuit pattern, a process of perforating the hole (17) on the insulative layer (15) by a laser beam, a process of roughing the surface of the insulative layer (15) by a dry etching process, a process of forming the conductive film (19) for a foundation of an electroplating process by a vacuum film forming method and a process of forming the conductive layer (20) on the conductive film (19) by an electroplating process so as to connect the conductive layer (20) with the circuit pattern (14) electrically. Accordingly, a printed circuit board having an extremely small anchor profile and a fine pattern can be manufactured in fewer manufacturing processes by utilizing the dry etching process and a sputtering film forming process.